

07-09-1998



FORM PTO-1595

REC

U.S. Department of Commerce  
Patent and Trademark Office

TIS-21040

100758331

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>1) Kian Teng Eng <b>NRD</b>  2) Min Yu Chan  3) Jing Sua Goh <b>6-26-98</b>  4) Siu Waf Low</p> <p>5) Boon Pew Chan  6) Tuck Fook Toh  7) Chee Kiang Yew  8) Pak Hong Yee</p>	<p>2. Name and Address of receiving party(ies):</p> <p>Name: TEXAS INSTRUMENTS INCORPORATED  Address: P.O. Box 655474, MS 3999  City: Dallas  State: TX Zip: 75265</p> <p>Additional name(s) &amp; address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
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3. Nature of Conveyance:

Assignment       Merger  
 Security Agreement       Change of Name  
 Other \_\_\_\_\_

Execution Date: *May 13, 1998, May 15, 1998, May 19, 1998 and May 20, 1998*

4. Application number(s) or patent number(s)

This document is being filed together with a new application.

Execution date of the application: *May 13, 1998, May 15, 1998, May 19, 1998 and May 20, 1998*

Title: *Method for Adhering and Sealing Silicon Chip in an Integrated Circuit Package*

Docket No: TIS-21040

<p>A. Patent Application No.(s)</p> <p><b>08/994,240</b></p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>B. Patent No.(s)</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
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<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: Mark E. Courtney  Texas Instruments Incorporated  Mail Station 3999  P.O. Box 655474  Dallas, Texas 75265</p>	<p>6. Number of applications and patents involved: <u>    (1)    </u></p>
<p>7. Amount of fee enclosed or authorized to be charged: \$40</p> <p style="text-align: center;">1 x \$40 = \$40</p>	
<p>8. Deposit Account No: 20-0668 (Attach duplicate copy if paying by deposit account) This form is submitted in triplicate.</p>	

07/01/1998 PA 154 00000029 200668 08994240  
64 10:54 40.00 00

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

June 23, 1998  
Date

*Mark E. Courtney*  
Mark E. Courtney, Reg. No. 36,491

ASSIGNMENT

TIS-21040

WHEREAS, the or each below named inventor (hereinafter INVENTOR) is the or an inventor of an invention for which a U.S. patent application has been filed as set forth below, and made the said invention in the course of employment by TEXAS INSTRUMENTS SINGAPORE (PTE) Limited, a company organized of according to the laws of Singapore, having an office at 990 Bendemeer Road, Singapore 1233, hereinafter (TIS);

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, Dallas, Texas 75251, is desirous of acquiring our entire right, title interest in and to the said invention outside of Singapore, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, effective as of December 19, 1997, TIS and INVENTOR(S) sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, the entire right, title and interest in and to the said invention in the U.S.A. and in all other countries outside Singapore; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TIS and INVENTOR hereby authorize and request the Commissioner of Patents to issue all U.S. patents for said invention, or patents resulting therefrom, insofar as our interest is concerned to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of the entire right, title and interest.

TIS and INVENTOR(S) further agree to communicate to TEXAS INSTRUMENTS INCORPORATED or to its successors, assigns and legal representatives, any facts known to them respecting the said invention, and at the expense of TEXAS INSTRUMENTS INCORPORATED, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally everything possible to said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside Singapore.

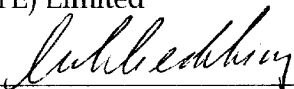
Title of Invention: **Method for Adhering and Sealing a Silicon Chip  
in an Integrated Circuit Package**

Inventor(s): Kian Teng Eng                      Boon Pew Chan  
                  Min Yu Chan                        Tuck Fook Toh  
                  Jing Sua Goh                            Chee Kiang Yew  
                  Siu Waf Low                           Pak Hong Yee

U.S. Application Serial No: 08/994,240      Filed: 12/19/97

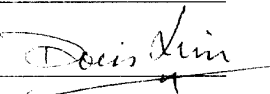
IN WITNESS WHEREOF, this Agreement has been executed as set forth below:

Signed at: Singapore on: 5/14/98  
by Texas Instruments Singapore (PTE) Limited

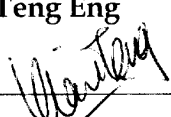
Name: Goh Geok Ling 

Title: Managing Director

Date: 5/14/98

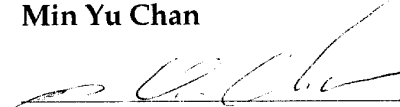
Witness: Doris Lim 

and by the INVENTOR(S):

Name: **Kian Teng Eng**  
Signature: 

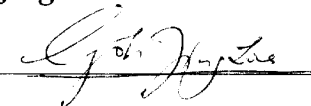
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Singapore 520332

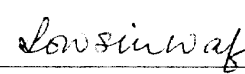
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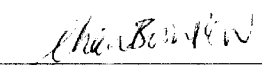
Name: **Min Yu Chan**  
Signature: 

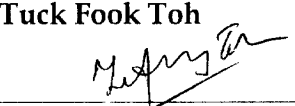
Address: Block 10F, Braddell Hill, #04-21  
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Date: 5/13/98

Name: **Jing Sua Goh**  
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Singapore 669506  
Date: 2-15/98

Name: **Siu Waf Low**  
Signature:   
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Date: 05/19/98

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Signature:  05/19/98  
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Date: 05/19/98

Name: **Tuck Fook Toh**  
Signature:   
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Singapore 570447  
Date: 05/19/98

Name: **Chee Kiang Yew**

Signature: \_\_\_\_\_

Address: Block 866, #04-313 Woodlands Street 83  
Singapore 730866

Date: \_\_\_\_\_

Name: **Pak Hong Yee**

Signature: \_\_\_\_\_

Address: Block 385, Pasir Panjang Road, #03-04 (Villa De West)  
Singapore 118719

Date: \_\_\_\_\_